EPISTAR

ES-FEGHPE05B

InGaN Green LED Chip

Features:

time

Applications:

High Power DensityLow Rth and Long life

· RGB Display Signage

> Mechanical Specification:

(1) Dimension

- Chip size: 5mil x 9mil (130 \pm 25 μ m x 240 \pm 25 μ m)

- Thickness: 3.9mil (100 \pm 10 $\mu m)$

- Anode pad: $50\pm$ 10 μ m x $80\pm$ 10 μ m

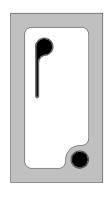
- Cathode pad: 50 \pm 10 μm x 80 \pm 10 μm

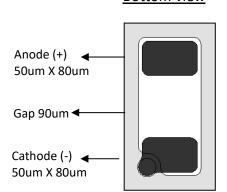
(2) Metallization

- Electrode pad: Au

Top view

Bottom view





> Electro-optical Characteristics at 25°C: (1)

Parameter	Symbol		Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf1		If = 10μA	1.8	-	-	V
	Vf2		If = 1mA	-	2.4	2.7	V
Reverse Current	lr		Vr = 10V	-	-	0.5	uA
Dominant Wavelength ⁽²⁾	λd		If = 1mA	525	-	540	nm
Spectra Half-width	Δλ		If = 1mA	-	35	-	nm
Luminous intensity ⁽³⁾	lv	I13	If = 1mA	70	-	90	- mcd
		114		90	-	110	
		I15		110	-	130	
		I16		130	-	150	

Note:

⁽¹⁾ ESD protection during chip handling is recommended.

 $^{(2) \} Basically, the \ wavelength \ span \ is \ 15 nm; \ however, \ customers' \ special \ requirements \ are \ also \ welcome.$

⁽³⁾ Luminous intensity is measured by EPISTAR's equipment on bare chips.

> Absolute Maximum Ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	Ta = 25°C	≤ 20	mA
Reverse Voltage	Vr	Ta = 25℃	≤ 10	V
Junction Temperature	Tj	-	≤ 115	٥
Storage Temperature	Tstg	Chip	-40 ~ +85	٥
		Chip-on-tape/storage	5 ~ 35	٥
		Chip-on-tape/transportation	-20 ~ +65	٥
Temperature during Packaging	-	-	260(<5sec)*	٥

Note: Maximum ratings are package dependent. The above maximum ratings were determined using by EPISTAR standard. Forward current and junction temperature will cause the damage of LEDs if over the absolute maximum ratings.

> Characteristic Curves:

Fig.1 – Relative luminous Intensity vs. Forward Current

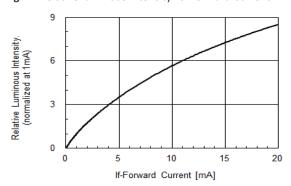


Fig.3 – Relative Intensity (@1mA) vs. Ambient Temperature

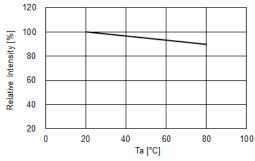


Fig.5 – Dominant Wavelength (@1mA) vs. Ambient Temperature

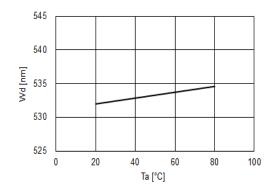


Fig.2 – Forward Current vs. Forward Voltage

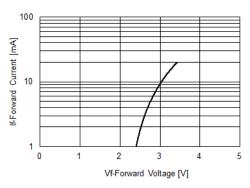


Fig.4 – Forward Voltage (@1mA) vs. Ambient Temperature

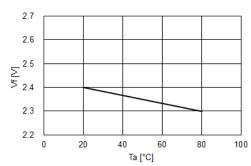
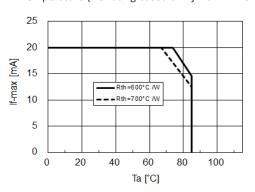


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on Tj max. = 115°C)



^{*}Reflow soldering should not be done more than two times.